

ABSTRACT OF THE DISCLOSURE

A semiconductor device has a first semiconductor chip and a second semiconductor chip superposed on and bonded to the surface of the first semiconductor chip. In the region on the first semiconductor chip where the second semiconductor chip is bonded thereto, connection pads are arranged in positions that fit a plurality of predetermined types of semiconductor chips. On the second semiconductor chip, connection pads are arranged in positions that fit the connection pads arranged on the first semiconductor chip.

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